

# 2023 Innovation and Technology Support Programme (Platform & Seed) open for applications

The Innovation and Technology Commission is inviting applications for the 2023 Innovation and Technology Support Programme (ITSP) (Platform & Seed) from today (July 24) until October 27.

The ITSP (Platform & Seed) provides funding support for platform and seed research and development (R&D) projects undertaken by designated local public research institutes and R&D centres. Platform projects are applied R&D projects that are industry-oriented and have potential for commercialisation, while seed projects are exploratory and forward-looking projects.

Further information is available on the Innovation and Technology Fund (ITF) website ([www.itf.gov.hk/en/funding-programmes/supporting-research/itsp/itsp-platform-seed/index.html](http://www.itf.gov.hk/en/funding-programmes/supporting-research/itsp/itsp-platform-seed/index.html)). For enquiries, please contact the ITF Secretariat (Tel: 3655 5678; email: [enquiry@itf.gov.hk](mailto:enquiry@itf.gov.hk)).